

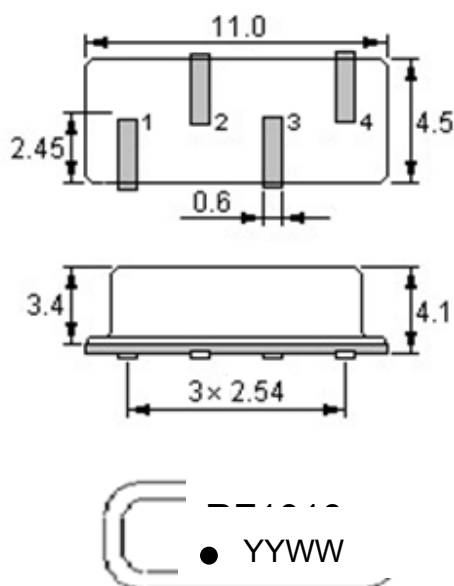
Application

- Low-loss SAW component
- Low amplitude ripple
- Sharp rejections at both out-bands
- Usable passband 1.5 MHz

Features

- RoHS compatible
- Package size 11.0x4.5x4.1mm³
- Package Code F11-SMD
- Electrostatic Sensitive Device(ESD)

Package Dimensions (Unit: mm)



Pin Configuration

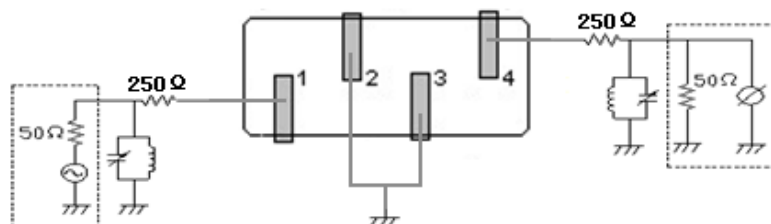
Pin No.	Description
1	Input
4	Output
2,3	Case Ground

Marking Description

RF	R	Trademark& Manufacturer
	F	SAW Filter
1010	Part Number	
●	Pin 1	
YYWW	Year Code & Week Code	

*Fig: If the products produced in 06th week of 2015,
The year code & week code is 1506.

Test Circuit (Bottom View)



Performance**Maximum Rating**

Item		Value	Unit
DC Voltage	V_{DC}	3	V
Operation Temperature	T	-40 ~ +85	°C
Storage Temperature	T_{stg}	-55 ~ +125	°C
RF Power Dissipation	P	15	dBm

Electronic Characteristics

Test Temperature: $25^{\circ}\text{C} \pm 2^{\circ}\text{C}$

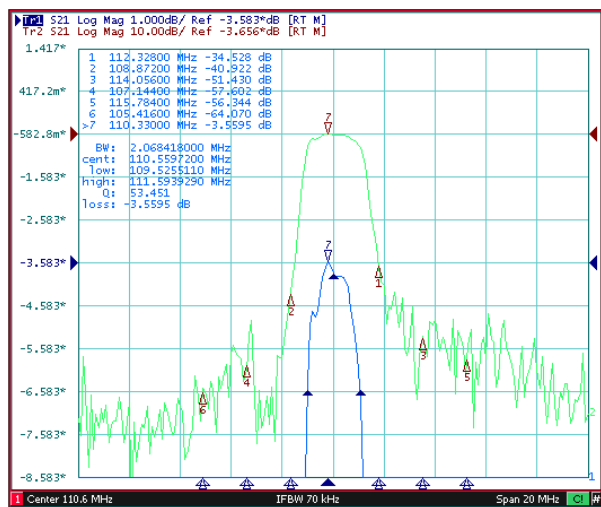
Terminating source impedance: 300Ω

Terminating load impedance: 300Ω

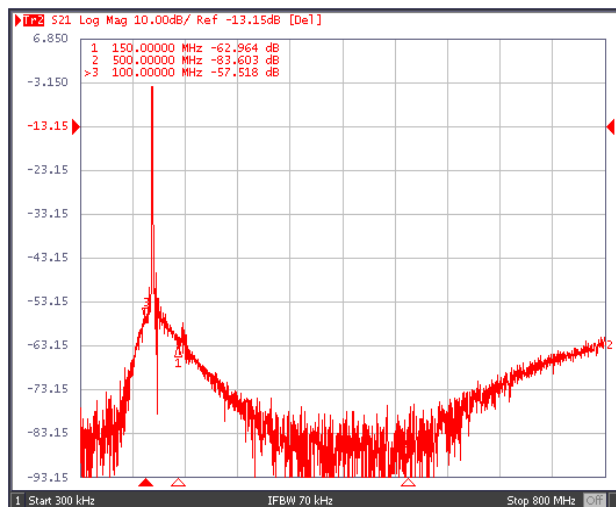
Item		Minimum	Typical	Maximum	Unit
Center Frequency	f_c		110.592		MHz
Insertion Loss(min)	IL		3.5	4.5	dB
Insertion Loss 109.85-111.35MHz	IL		4.8	5.5	dB
Amplitude Ripple (p-p) 109.85-111.35MHz	Δa		1.2	1.8	dB
Group Delay Ripple 109.85-111.35MHz			500	800	ns
Absolute Attenuation	a				
DC-100.000 MHz		45.0	50.0		dB
105.416-107.144MHz		40.0	45.0		dB
107.144-108.872MHz		35.0	40.0		dB
112.328-114.056MHz		25.0	28.0		dB
114.056-115.784MHz		35.0	40.0		dB
150.000-800.000MHz		50.0	55.0		dB
Input VSWR 109.85-111.35MHz			2.0:1	2.5:1	/
Output VSWR 109.85-111.35MHz			2.0:1	2.5:1	/

Frequency Characteristics

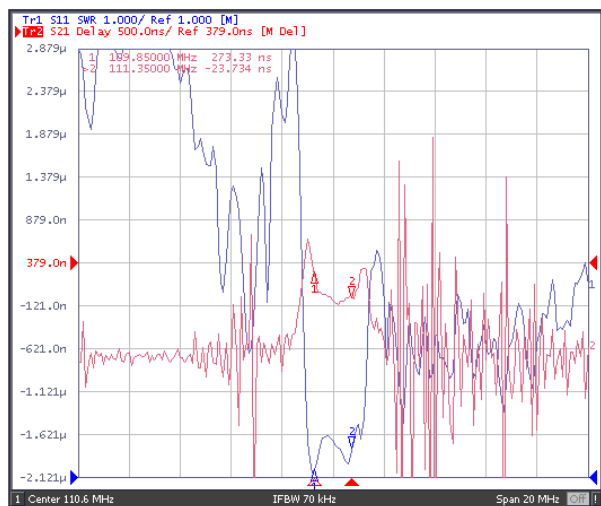
Frequency Response



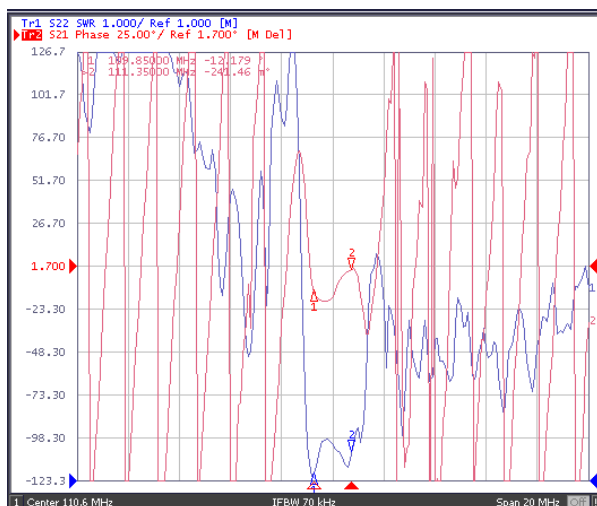
Frequency Response (wideband)



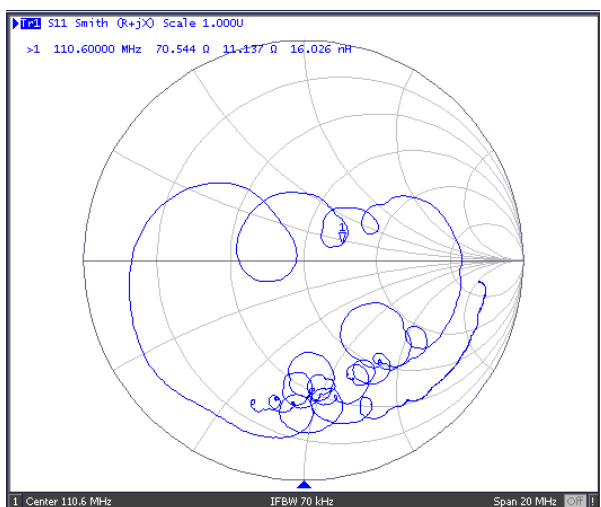
Delay Ripple & S11 VSWR



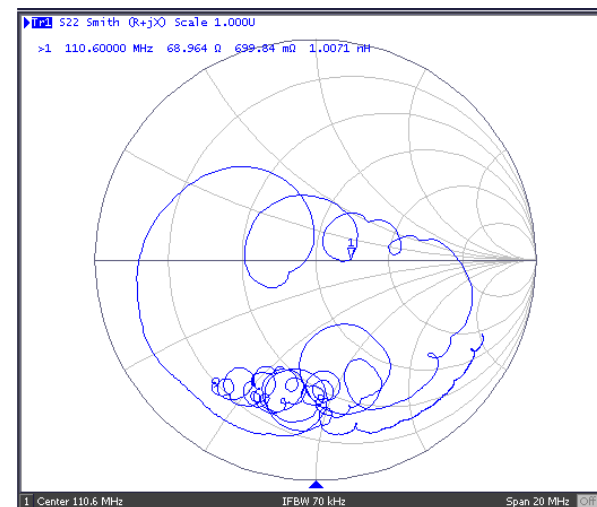
Phase Linearity & S22 VSWR



S11 Smith Chart



S22 Smith Chart



Notes

1. As a result of the particularity of inner structure of SAW products, it easy to be breakdown by electrostatic, so we should pay attention to **ESD protect** in the test.
2. **Static voltage** between signal load and ground may cause deterioration and destruction of the component. Please avoid static voltage.
3. **Ultrasonic cleaning** may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
4. Only leads of component may **be soldered**. Please avoid soldering another part of component.
5. There is a close relationship between the device's performance and **matching network**. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.